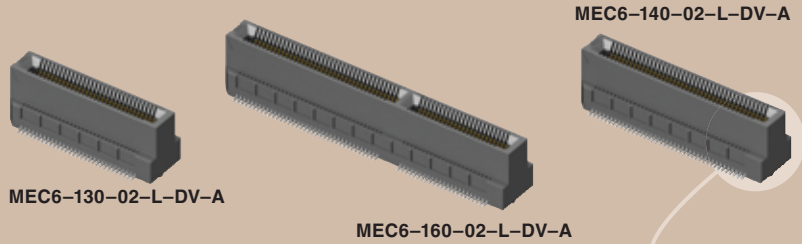




(0,635 mm) .025"

MEC6-DV SERIES



VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50µ" (1,27 µm) Ni

Operating Temp Range:

-55°C to +125°C

Insertion Depth:

(4,22 mm) .166" to

(5,66 mm) .223"

Current Rating:

Testing Now!

Voltage Rating:

Testing Now!

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)



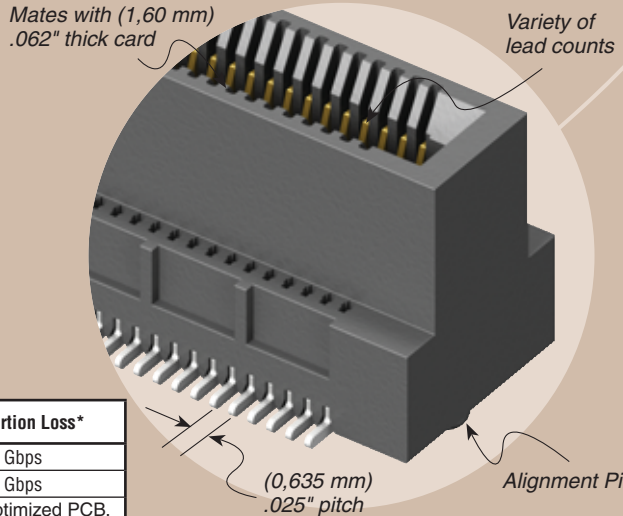
Mates with:
(1,60 mm) .062" thick cards

APPLICATION SPECIFIC OPTION

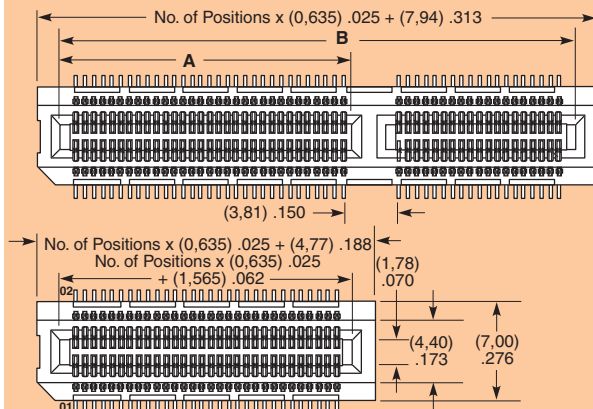
- Locking Clip (Manual placement required)
- Call Samtec.

MEC6-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?MEC6-DV or contact sig@samtec.com



10, 20, 30, 40, 50, 60, 70



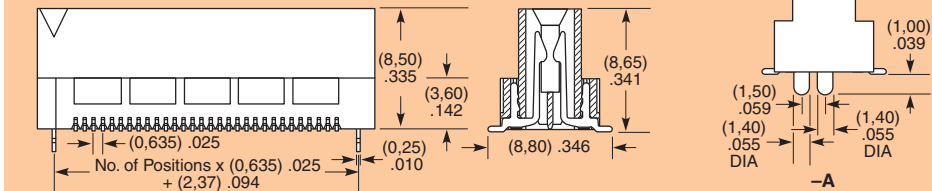
-L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

Note: Other Gold plating options available. Contact Samtec.

-K
= (5,50 mm)
.217" DIA
Polyimide Pick & Place Pad

-TR
= Tape & Reel

POSITIONS PER ROW	A	B
50	(22,96) .904	(36,49) 1.437
60	(24,87) .979	(42,84) 1.687
70	(28,68) 1.129	(49,19) 1.937



Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM